



Physics and Mechanics of New Materials and Their Applications 2021

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Deadline for manuscript
submissions:

closed (10 September 2022)

Message from the Guest Editors

Dear Colleagues,

The present Special Issue aims to explore new trends in these scientific and technical areas. A certain number of contributions for this Special Issue will come from selected papers of PHENMA 2021. You will also have an opportunity to enjoy special 10% discounts for your submission to the Special Issue.

Topics of interest (among others) include:

- **Materials:** ferro-piezoelectrics, semiconductors, superconductors, environmental materials.
- **Synthesis and Processing:** powder processing, processing technologies.
- **Characterization and Research Methods:** material design, microstructure properties.
- **Applications:** MEMS, hetero-structures, piezotransducers, energy harvesting.
- **Underwater Technologies:** underwater communication, marine engineering.
- **Biomedical Engineering:** medical materials, nanotechnology in medicine, medical instrumentation.
- **Industry and Management:** CAD/CAM/CAE application, industrial instruments.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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